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Reply Under 37 CFR 1.116
Expedited Procedure - Technology Center 1700

PATENT

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TC 1700

In re application of:

TAGUCHI ET AL

Serial No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

Examiner: C. Cooke

For: LEAD-FREE SOLDER PASTE FOR REFLOW SOLDERING

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

An amendment in the above-identified patent application is attached.

[x] No additional claim fee is required.

[] The claim fee has been calculated as shown below:

(Col. 1)		(Col. 2)		(Col. 3)	SMALL ENTITY		OTHER THAN A SMALL ENTITY	
////////	CLAIMS	////////	HIGHEST					
////////	REMAINING	////////	NO.					
////////	AFTER	////////	PREVIOUSLY	PRESENT		ADDIT.		ADDIT.
////////	AMENDMENT	////////	PAID FOR	EXTRA	RATE	FEE	RATE	FEE
TOTAL	* 21	MINUS	** 24	= 0	x 9=	\$	x 18=	\$ 0
INDEP	* 2	MINUS	*** 3	= 0	x 43=	\$	x 86=	\$ 0
FIRST PRESENTATION OF MULT. DEP. CLAIM					+145	\$	+290=	\$
					TOTAL	\$	TOTAL	\$ 0

* If entry in Col. 1 is less than that in Col. 2, write "0" in Col. 3.

** If the highest no. previously paid for IN THIS SPACE is less than 20, write "20" in this space.

*** If the highest no. previously paid for IN THIS SPACE is less than 3, write "3" in this space.

- [] A check in the amount of _____ is attached.
- [] Please charge Deposit Account No. 50-1079 in the amount of \$.
- [] The Commissioner is authorized to charge any deficiency in the following fees associated with this communication and to credit any excess payment to Deposit Account No. 50-1079. A duplicate copy of this letter is attached.
- [] Any filing fees pursuant to 37 CFR §1.16 for the presentation of extra claims.
- [] Any patent application processing fees pursuant to 37 CFR §1.17, including extension of time fees pursuant to 37 CFR §1.17(a)-(d).

Respectfully submitted,

Michael Tobias

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Date: October 8, 2003



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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE
BEFORE THE BOARD OF PATENT APPEALS AND INTERFERENCES

In re application of:

TAGUCHI ET AL

Application No.: 09/642,765

Art Unit: 1725

Filed: August 22, 2000

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For: LEAD-FREE SOLDER PASTE
FOR REFLOW SOLDERING

AMENDMENT UNDER 37 CFR 1.116

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Examiner's Answer mailed on August 22, 2003 in connection with the present application, the Applicants respectfully request that the present application be amended as shown below.